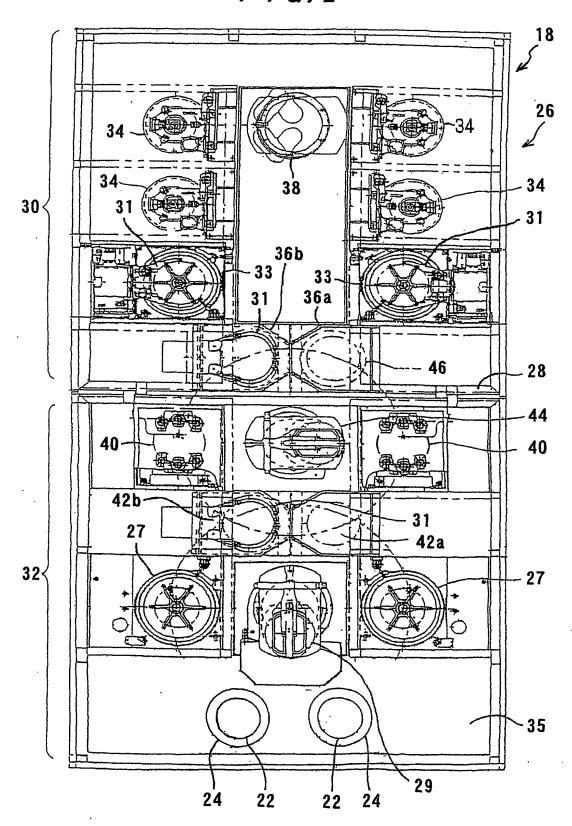
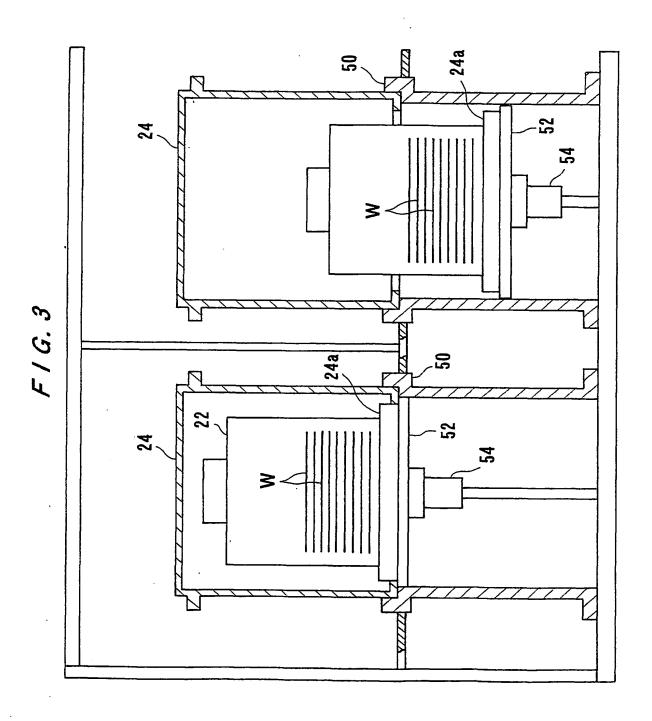


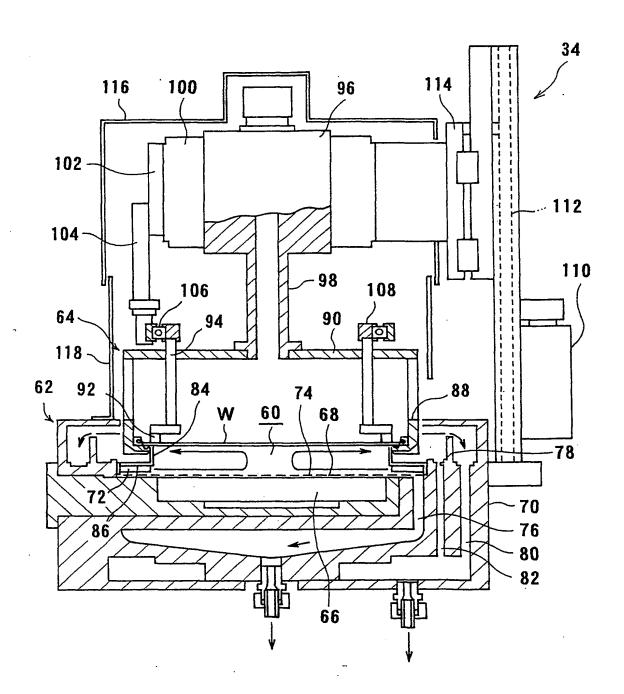
2/89 F I G. 2

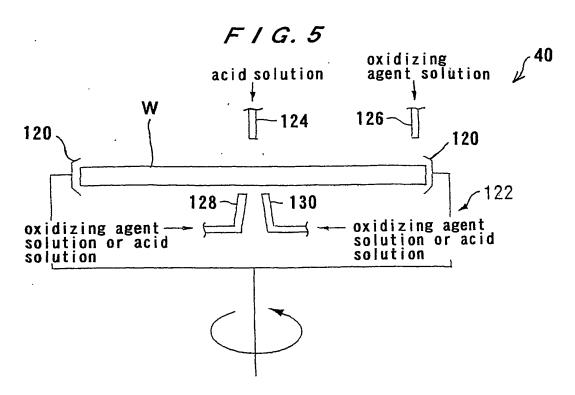


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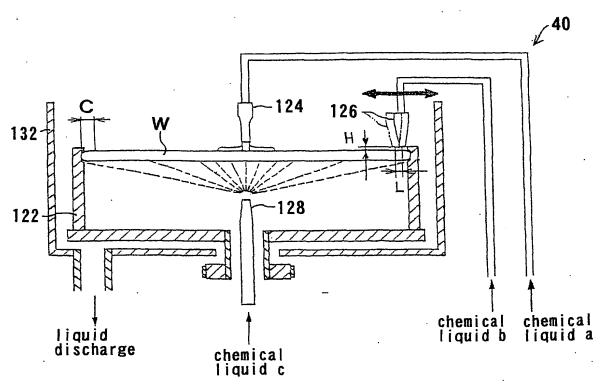


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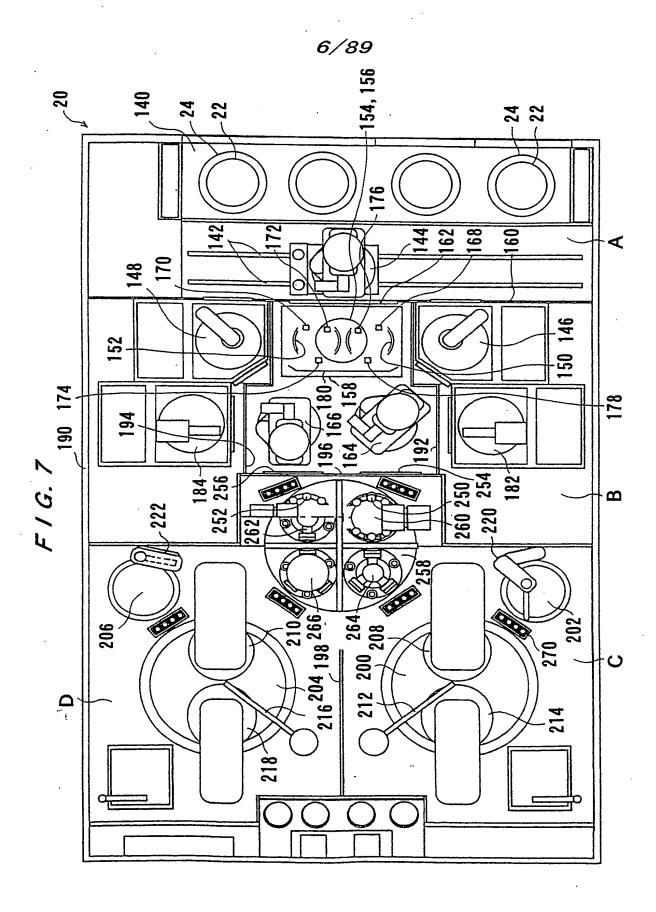


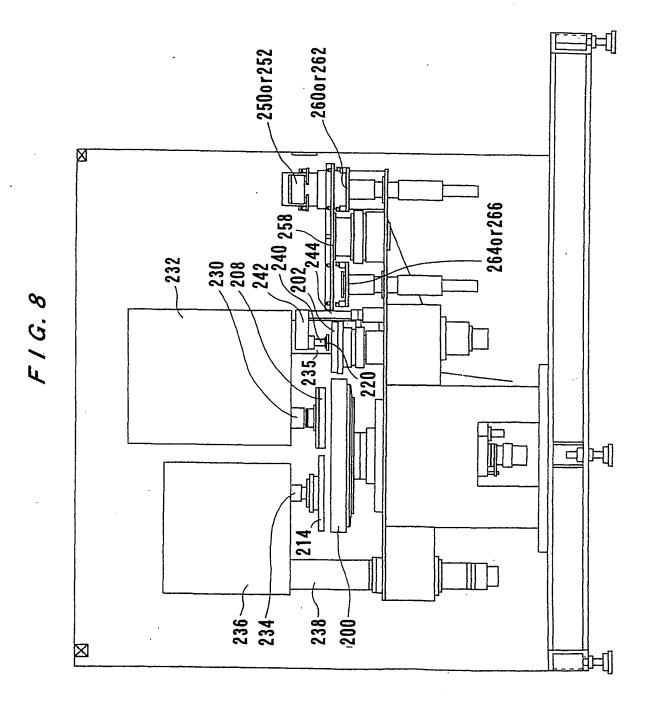


F 1 G. 6

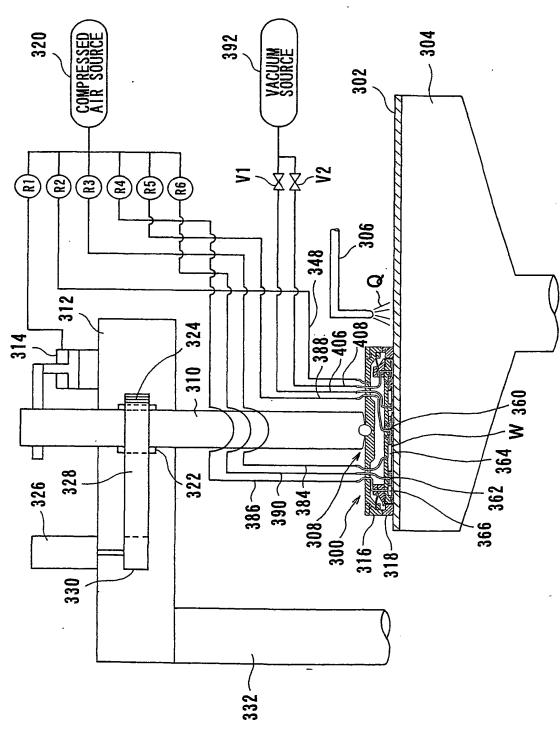


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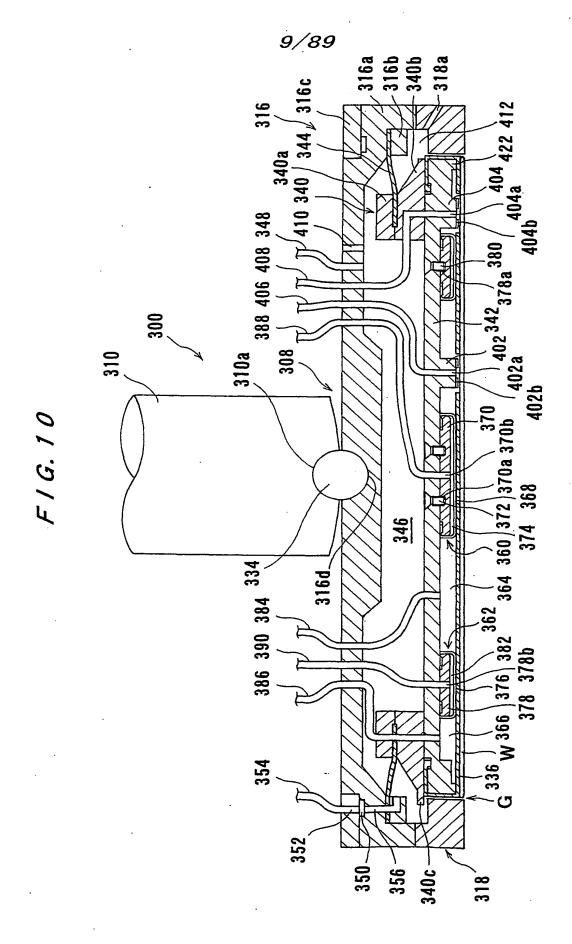




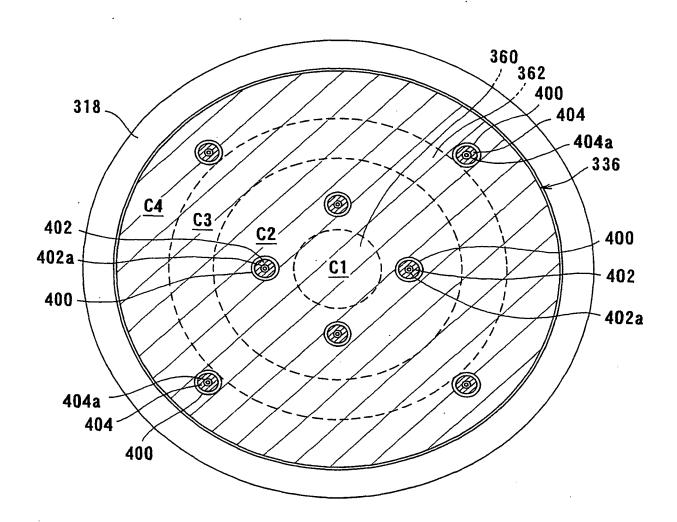
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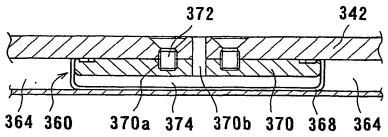
... ...



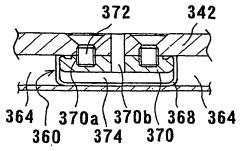
F/G.11



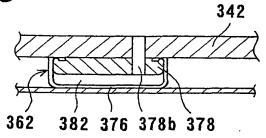




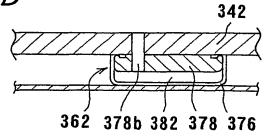
F I G. 12B



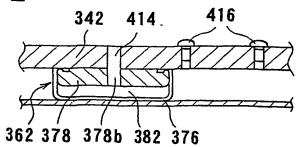
F / G. 12C



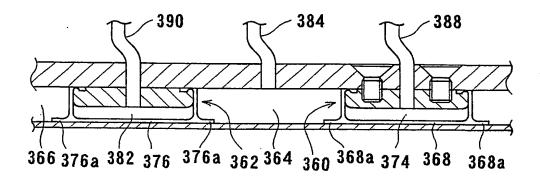
F / G. 12D



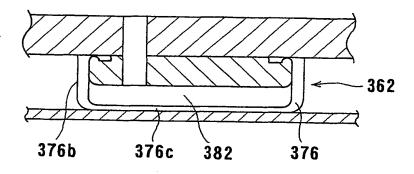
F / G. 12E



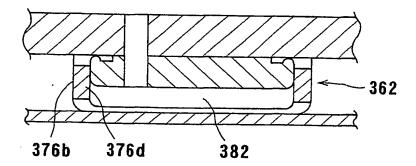
## F/G.13



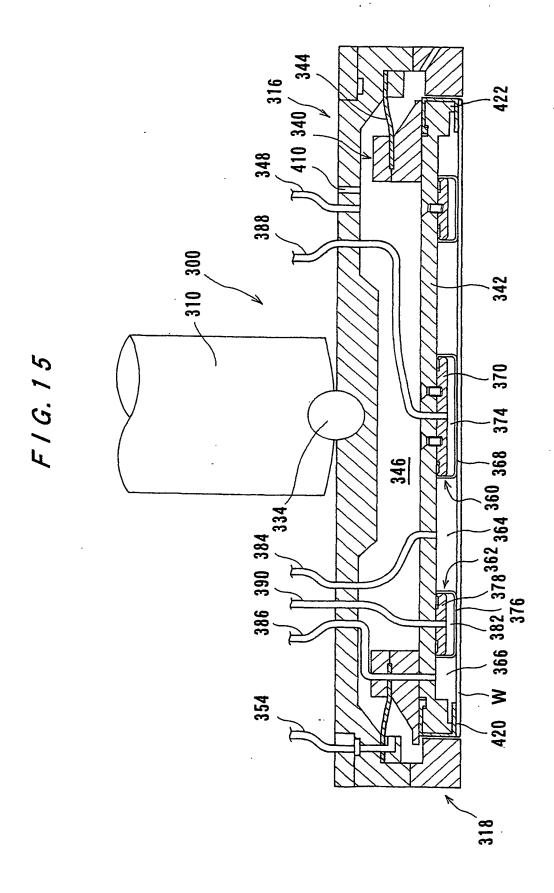
F / G. 14A



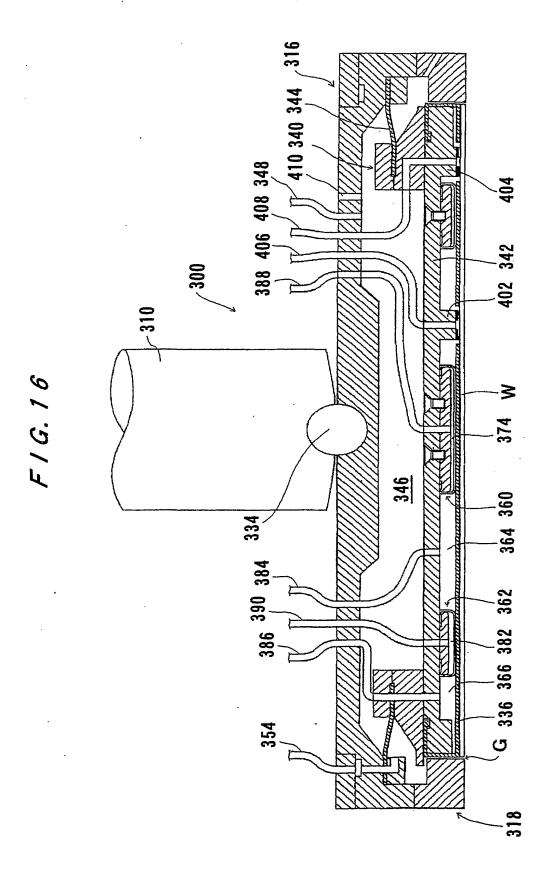
F / G. 14B



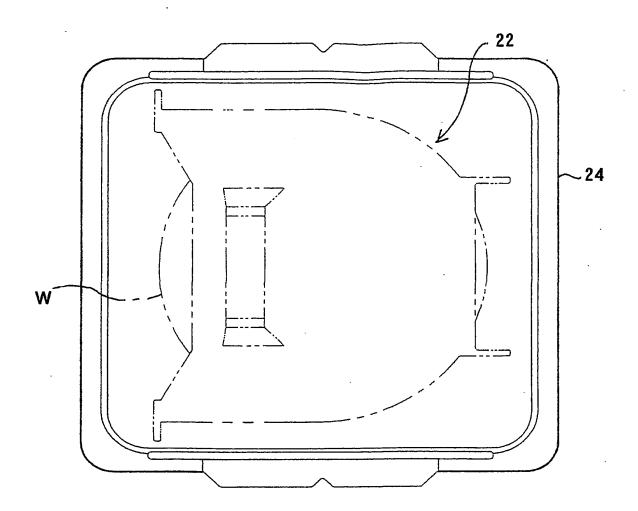
14/89



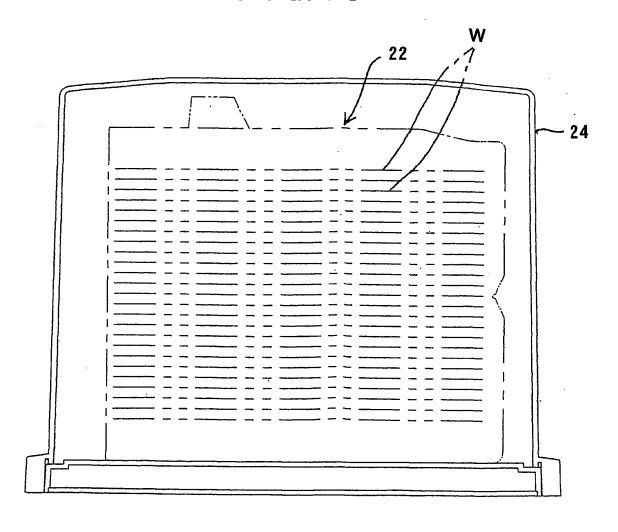
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F/G.17



F/G.18



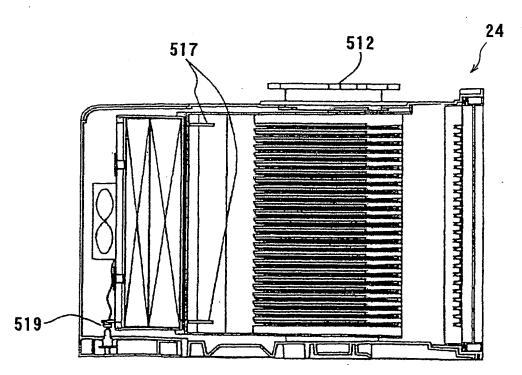


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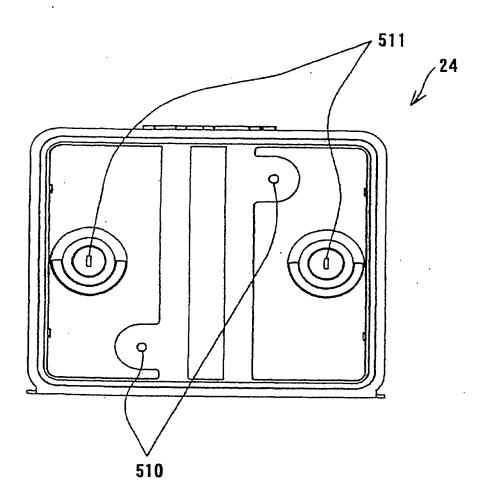
F I G. 19 24 501 513b 502 513a 503 -515 507 Α 514 516 506 505 513b 530 **5**04

F / G. 20

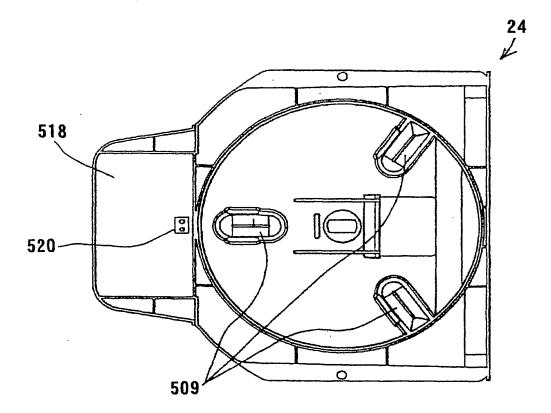




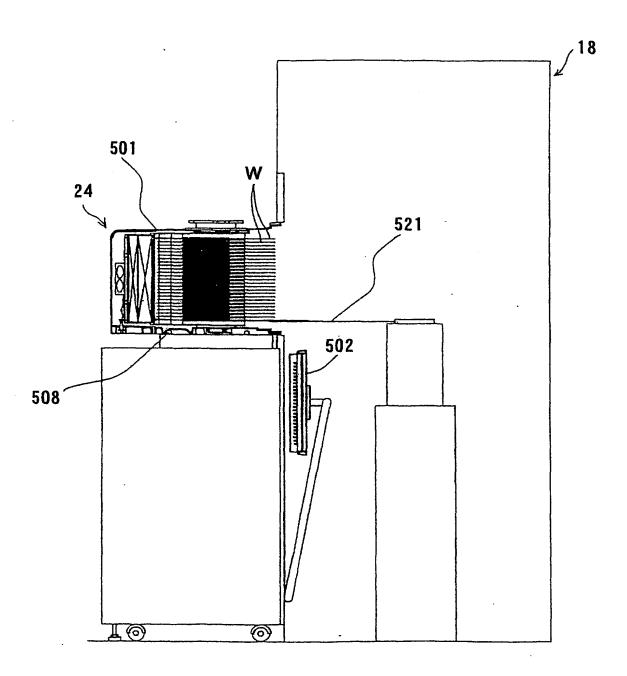
F | G. 21



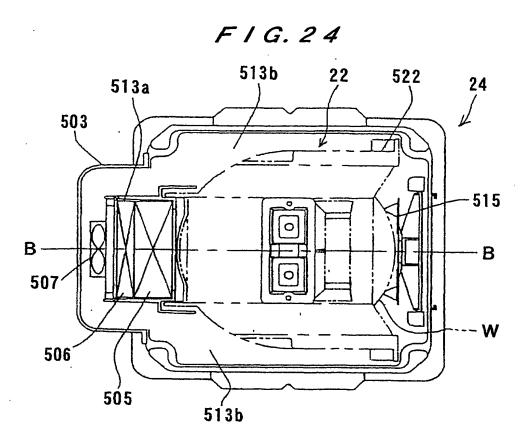
F 1 G. 22



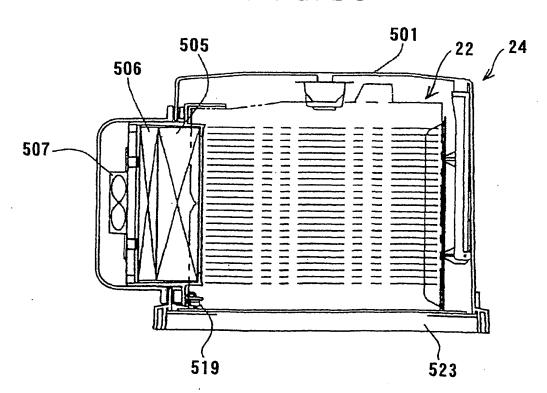
F I G. 23



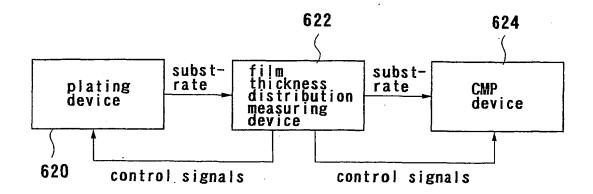
22/89

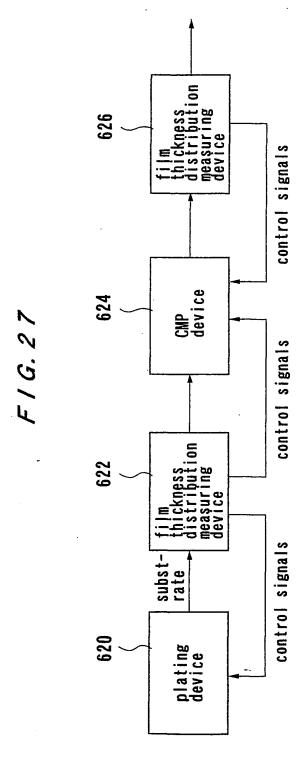


F | G. 25

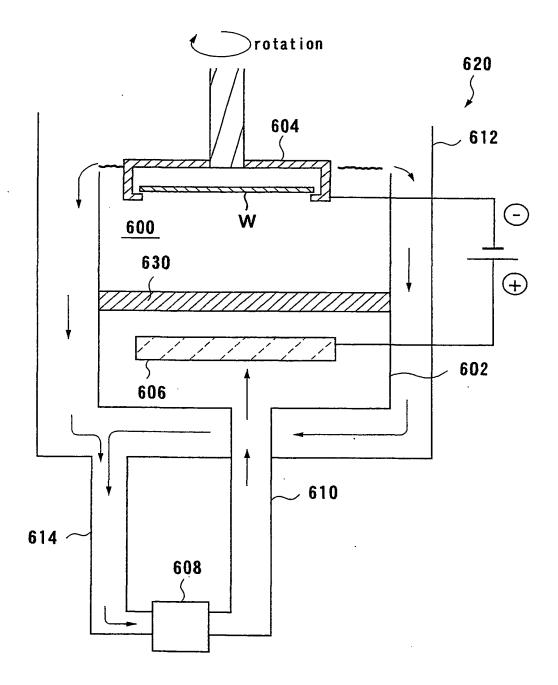


F 1 G. 26



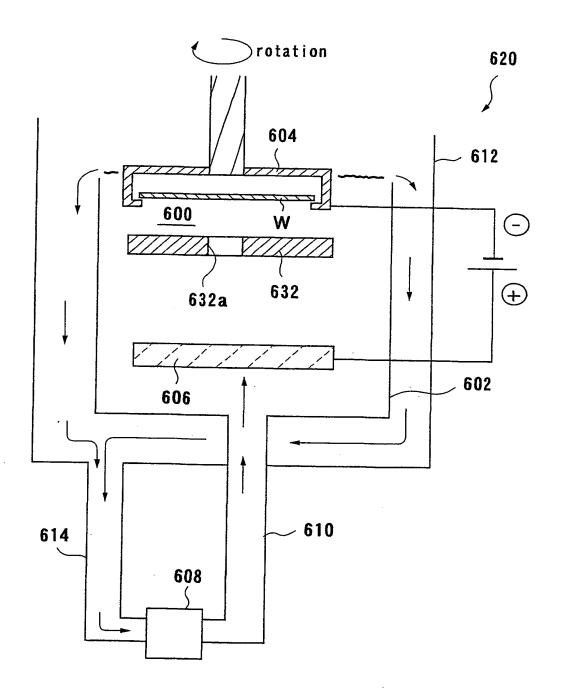


F I G. 28

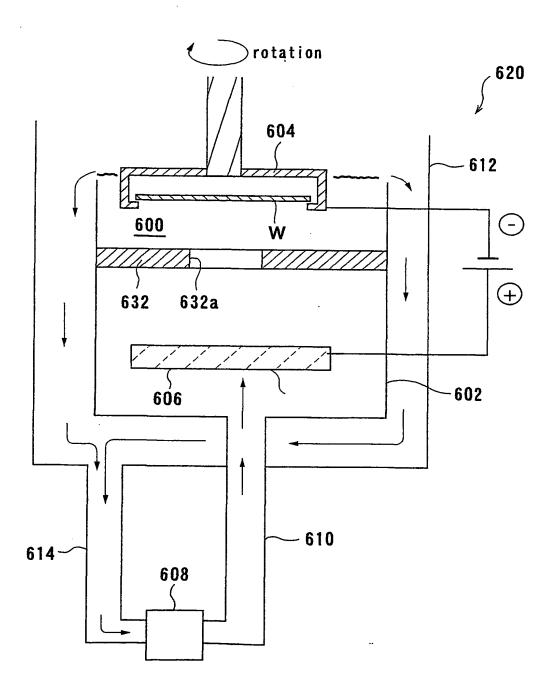


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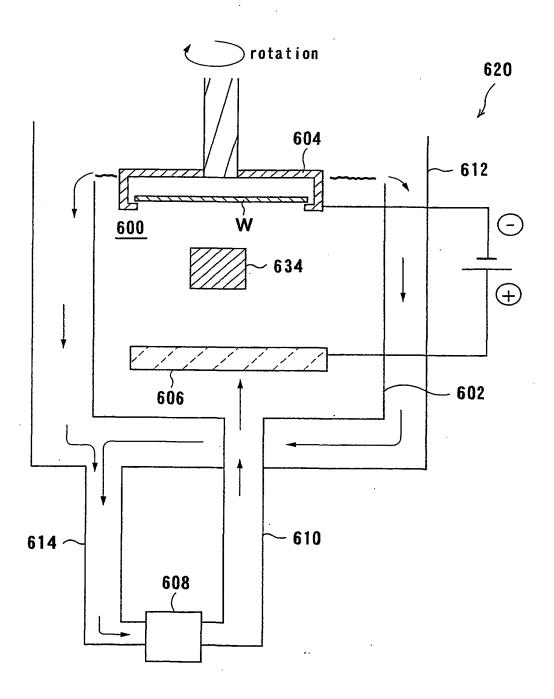
F | G. 29



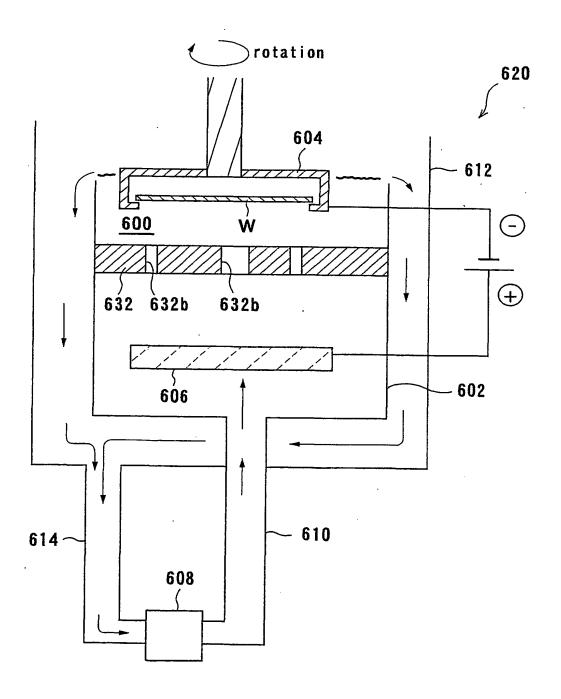
F | G. 30



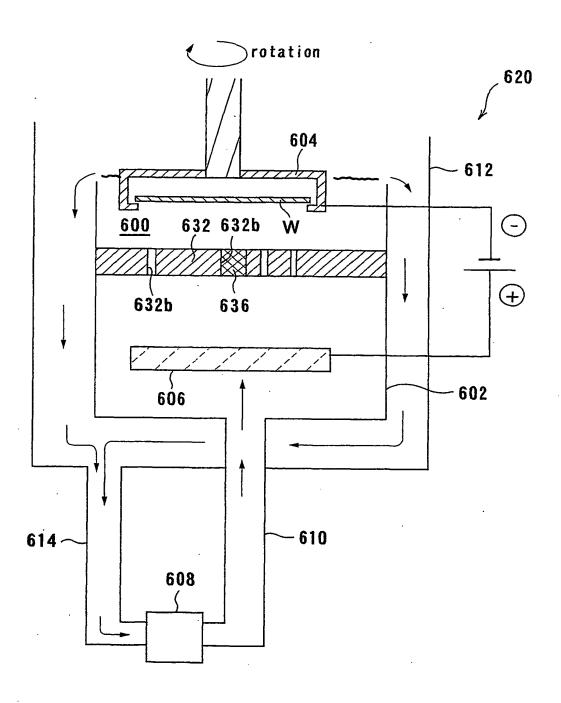
F | G. 3 1



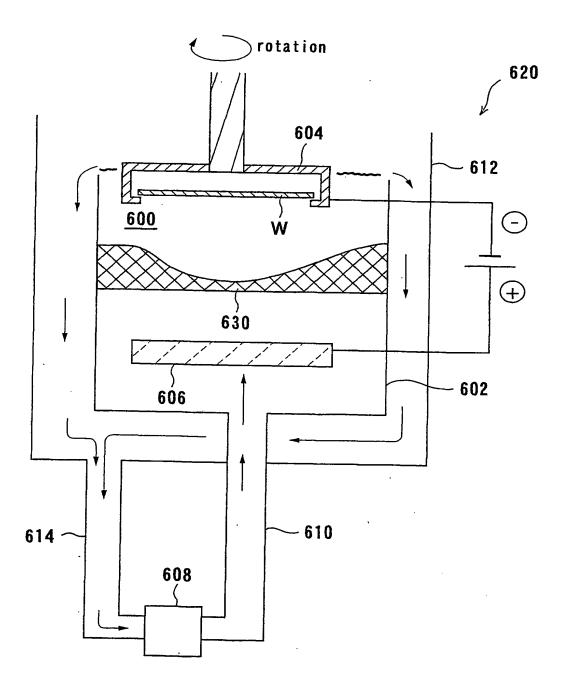
F / G. 32



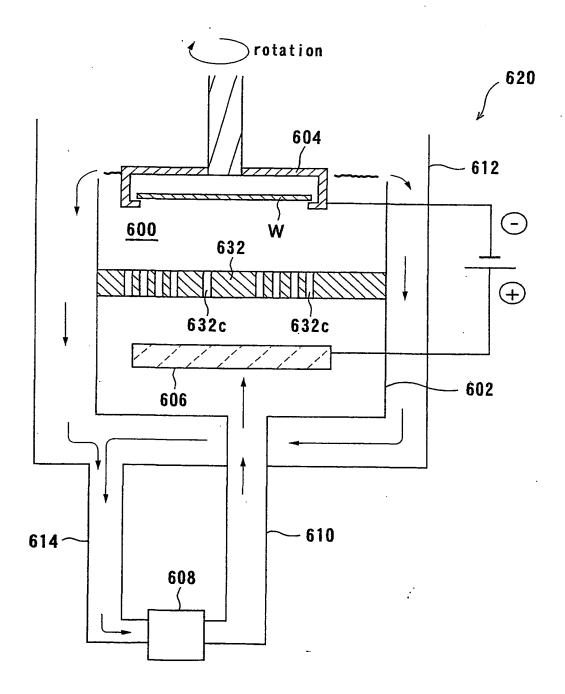
F / G. 33



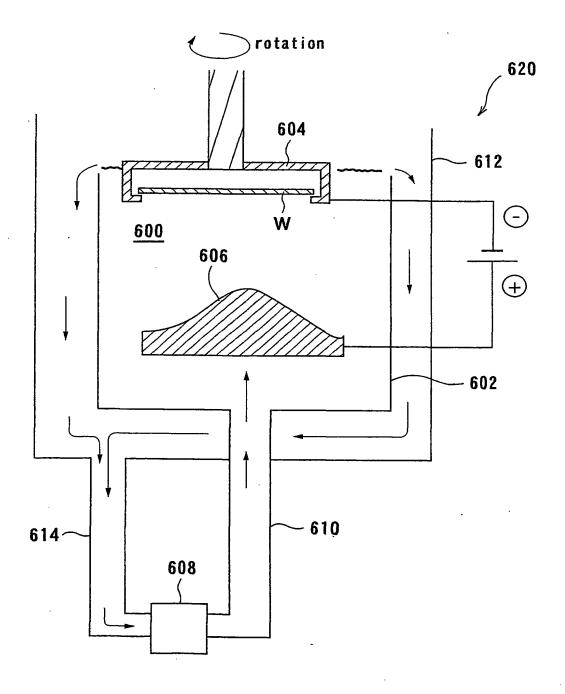
F / G. 34



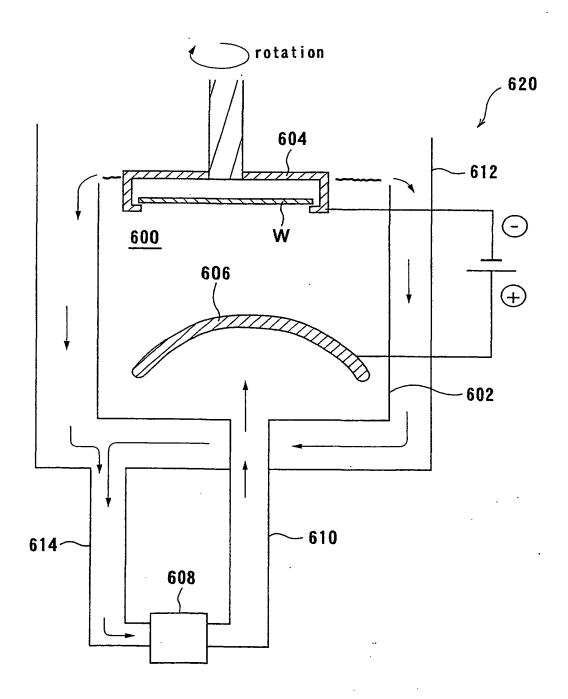
F / G. 35



F 1 G. 36

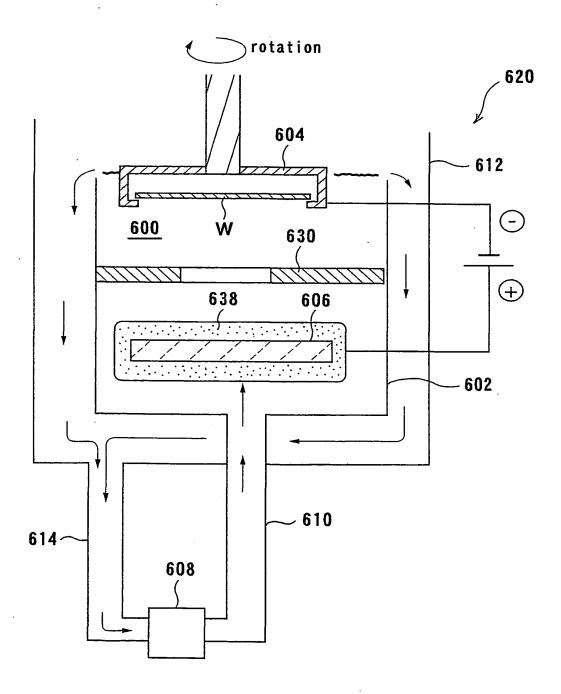


F | G. 37



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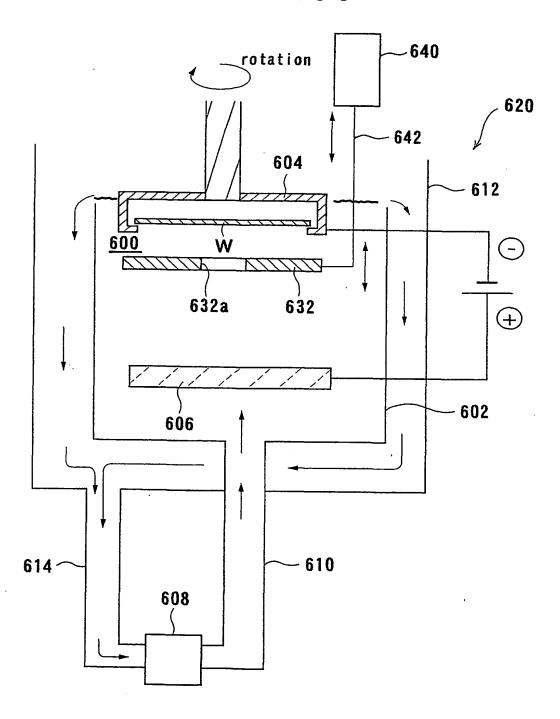
F | G. 38



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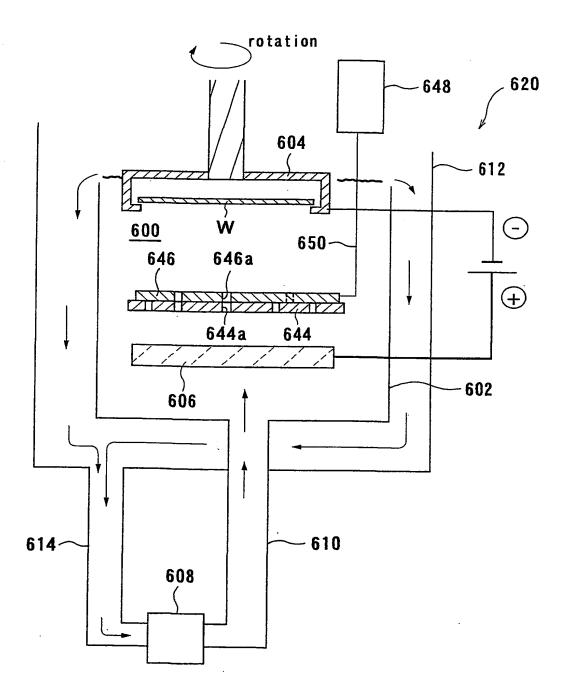
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F | G. 39

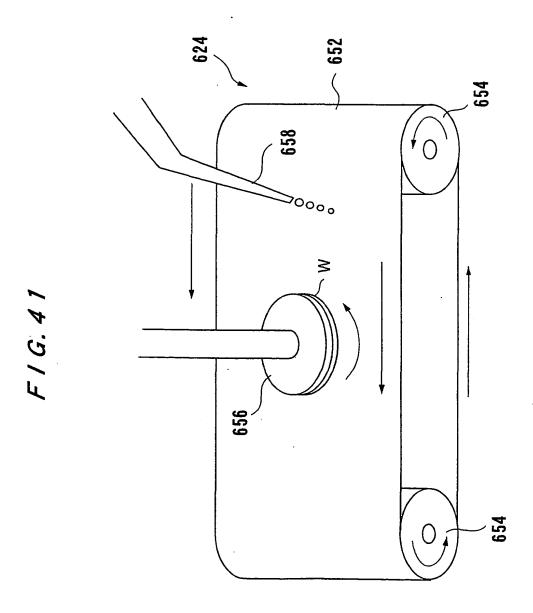


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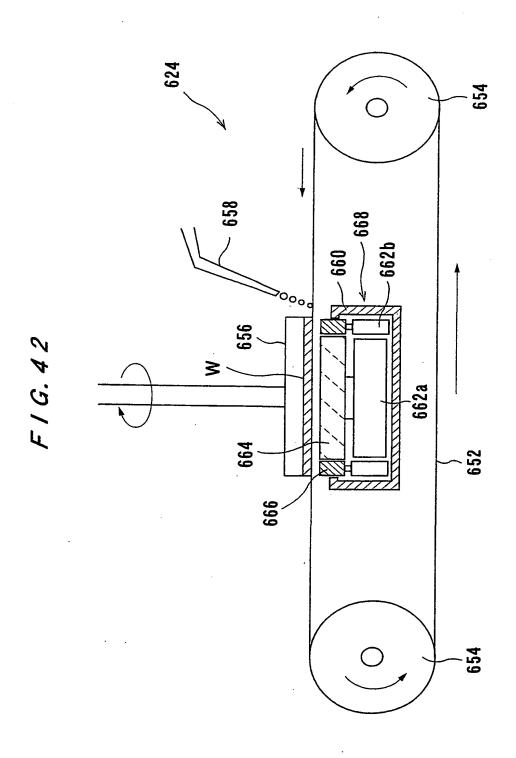
F / G. 40



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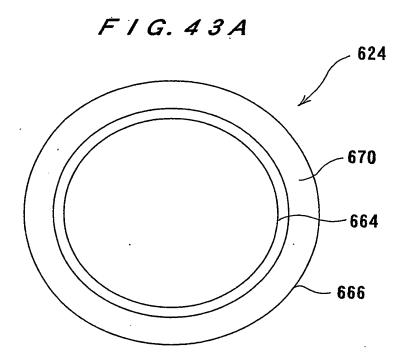


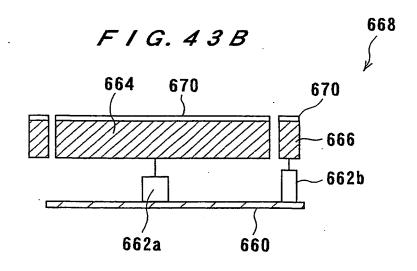
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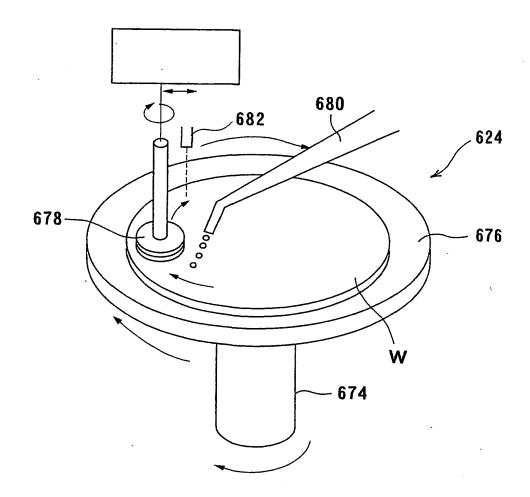
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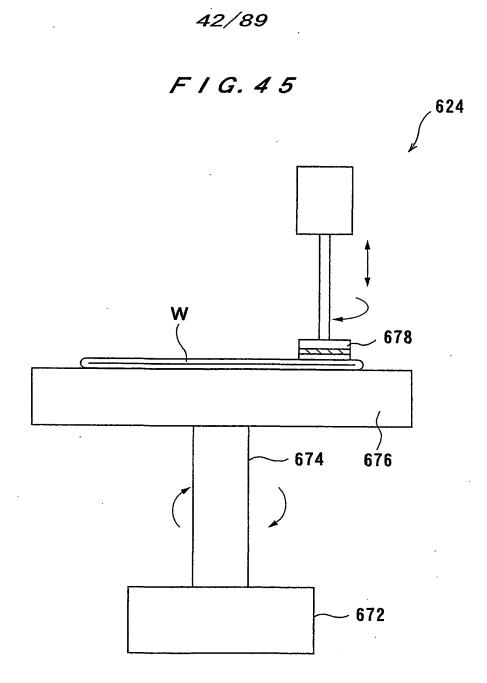


F 1 G. 44

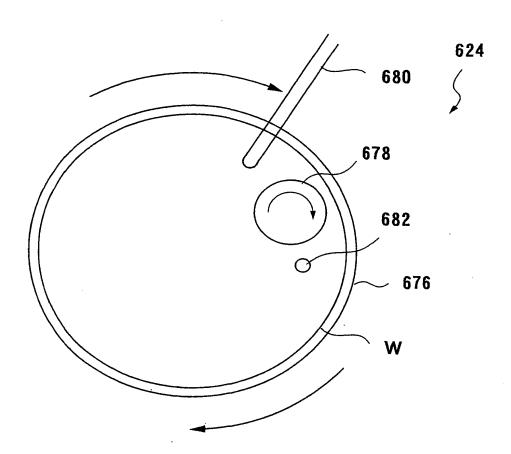


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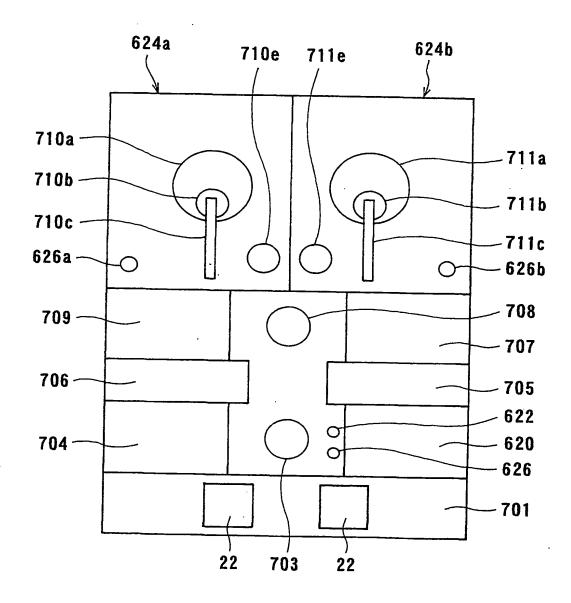




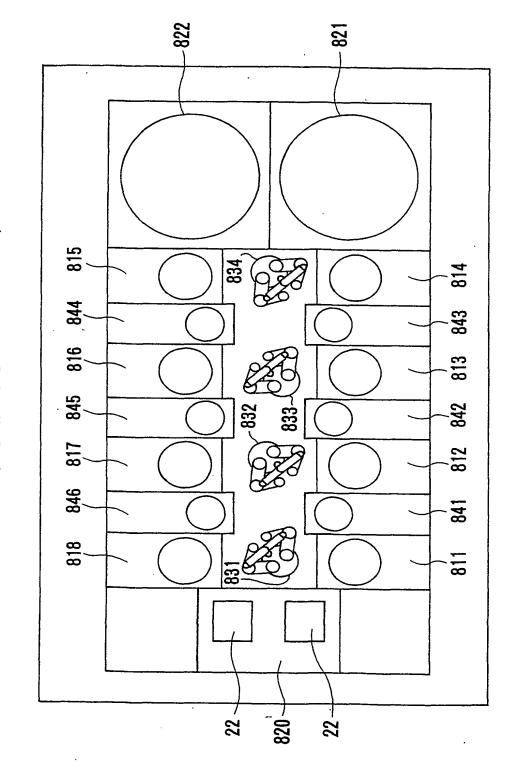
F | G. 46



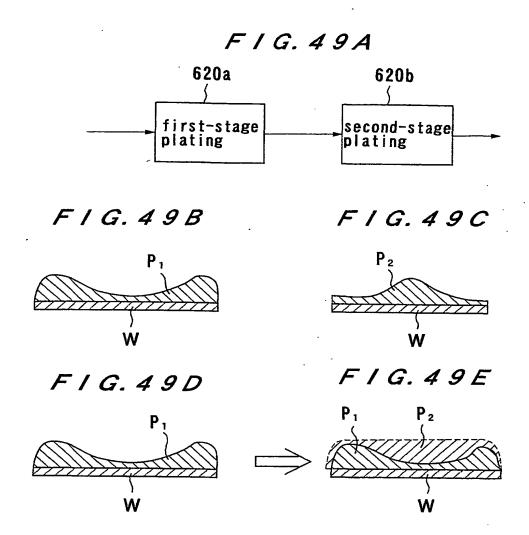
F I G. 47



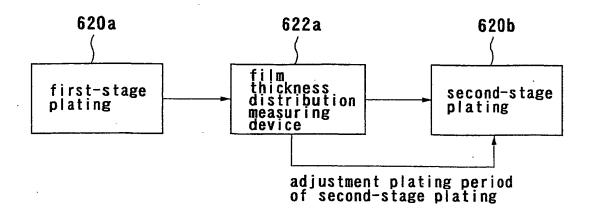
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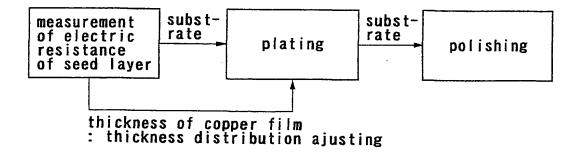
F1G.48



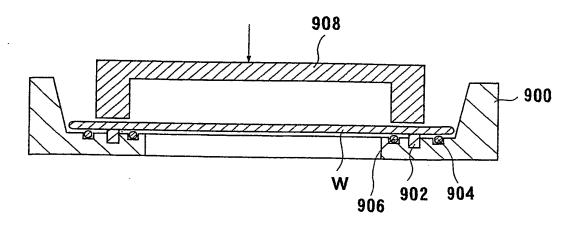
F 1 G. 50



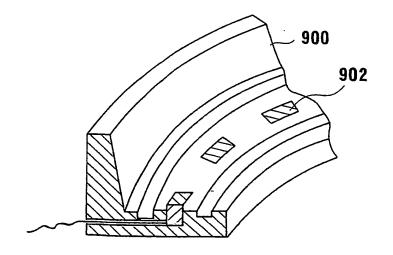
F | G. 5 1



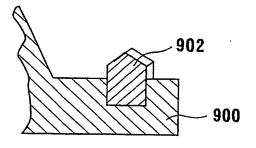
F/G.52



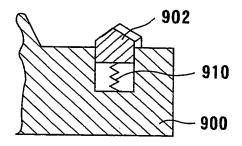
F/G.53



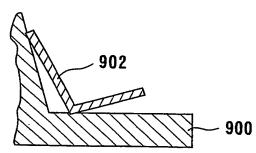
F | G. 54A



F | G. 54B

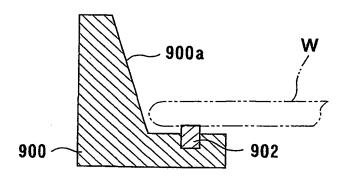


F | G. 54C

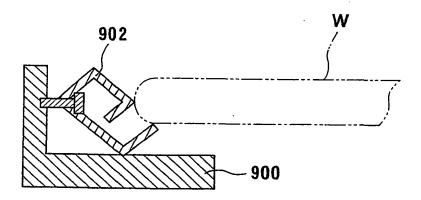


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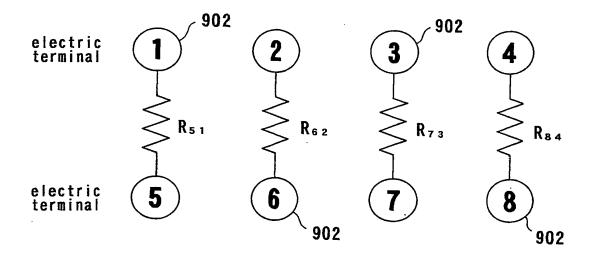
F / G. 55A



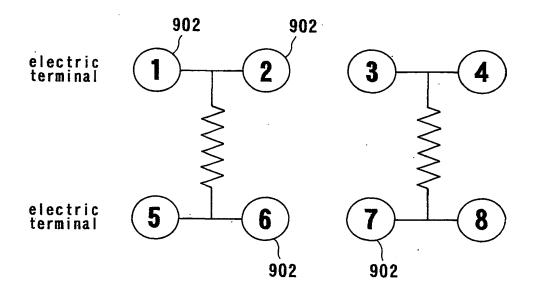
F / G. 55B



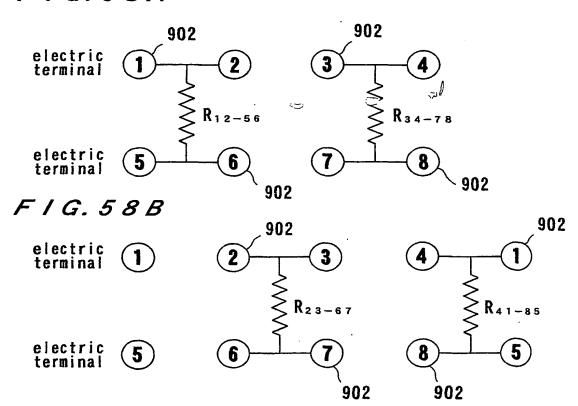
F/G.56



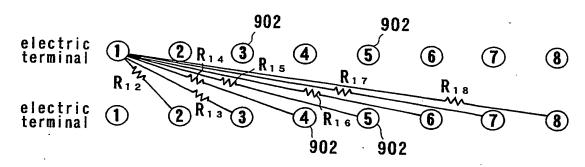
F | G. 57



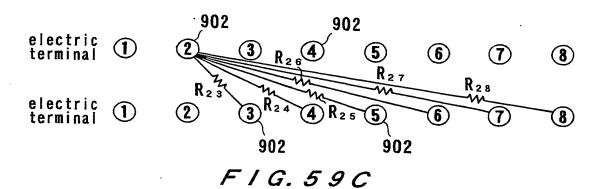
## F | G. 58A

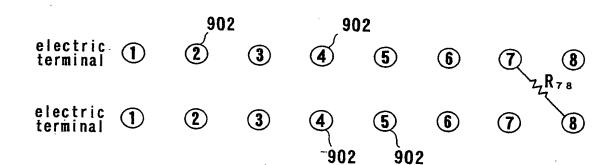


### F I G. 59A

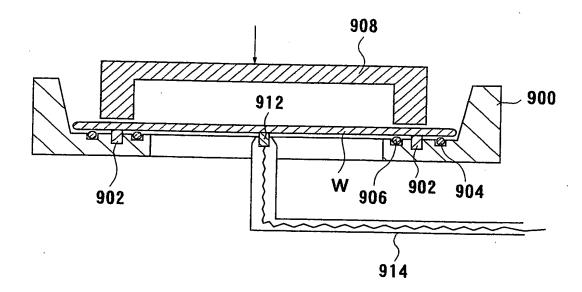


F | G. 59B

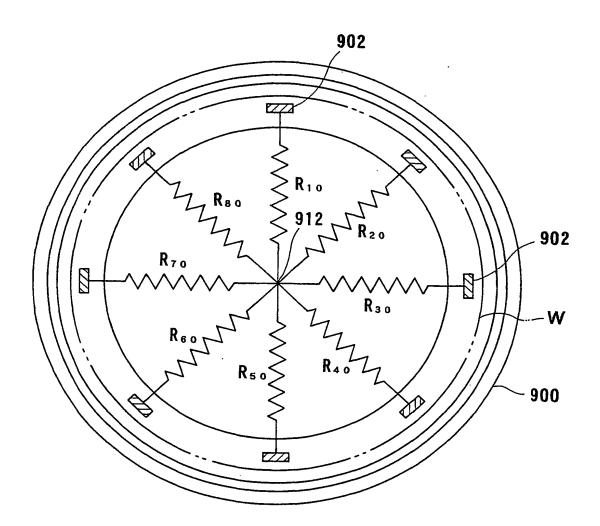




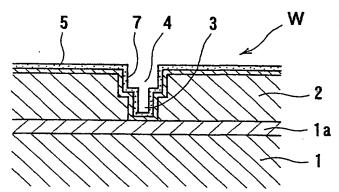
F/G.60

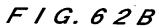


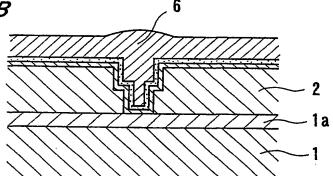
F | G. 6 1



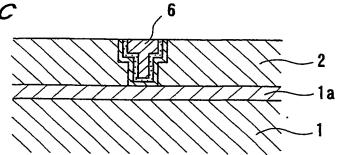
F I G. 62A







F/G.62C

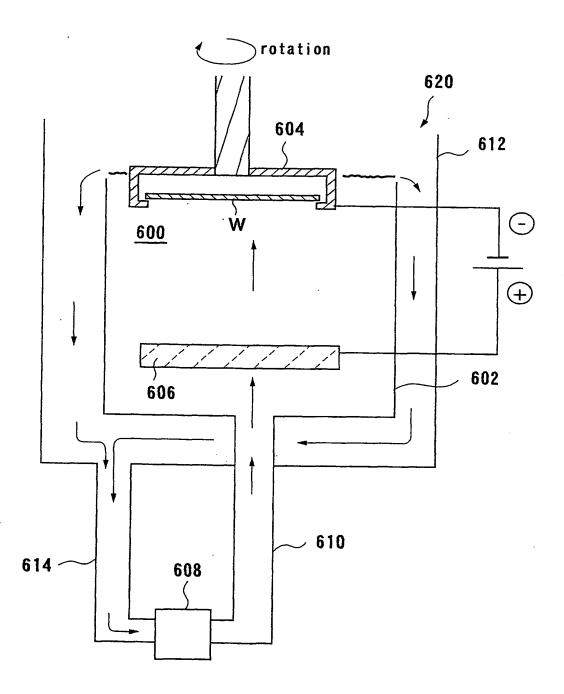


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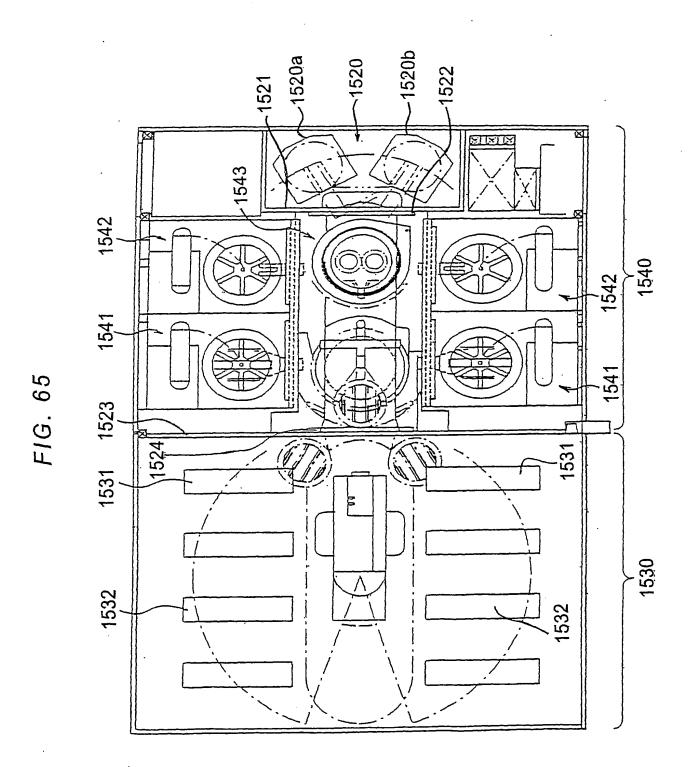
CMP device 20 copper plating device 22 seed layer forming device 16 barrier layer forming device isolation film forming device

F1G.63

F 1 G. 64



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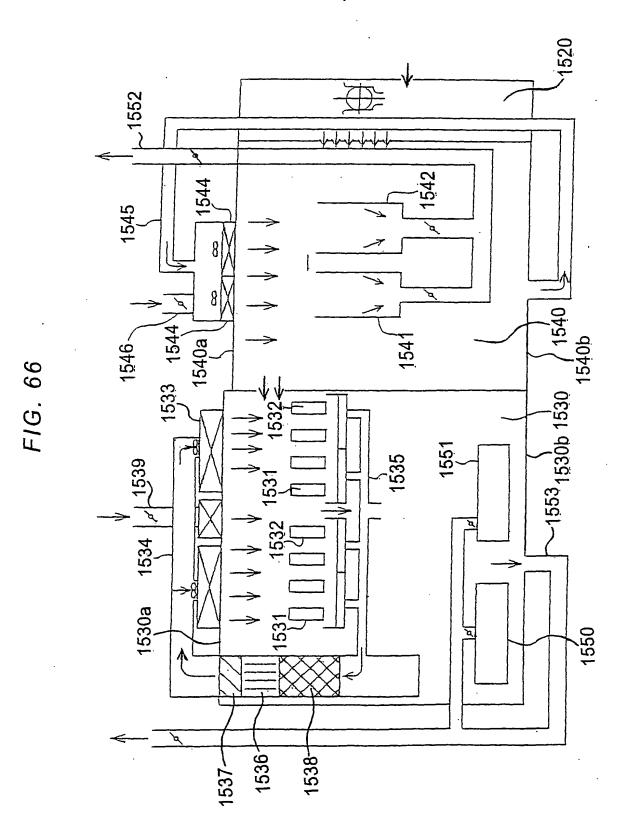


FIG. 67

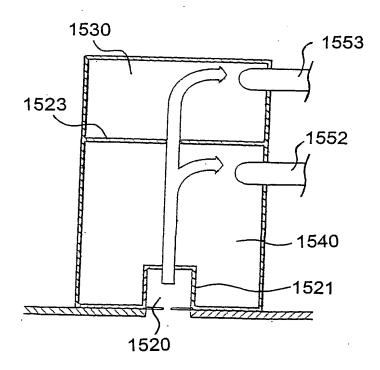


FIG. 68

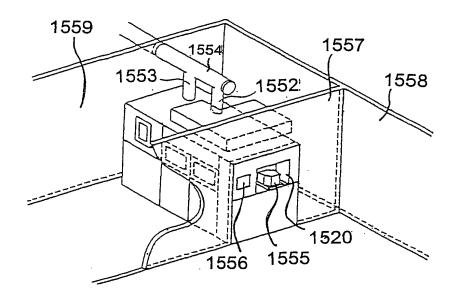
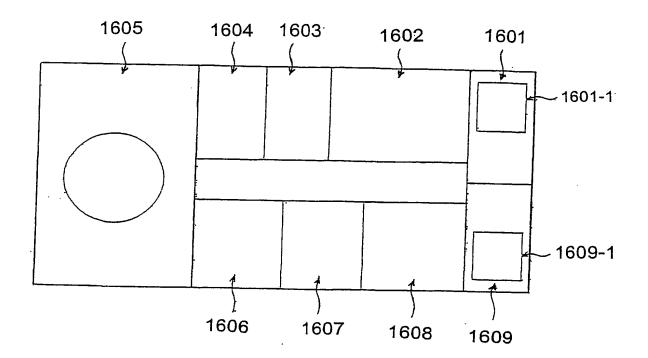


FIG. 69



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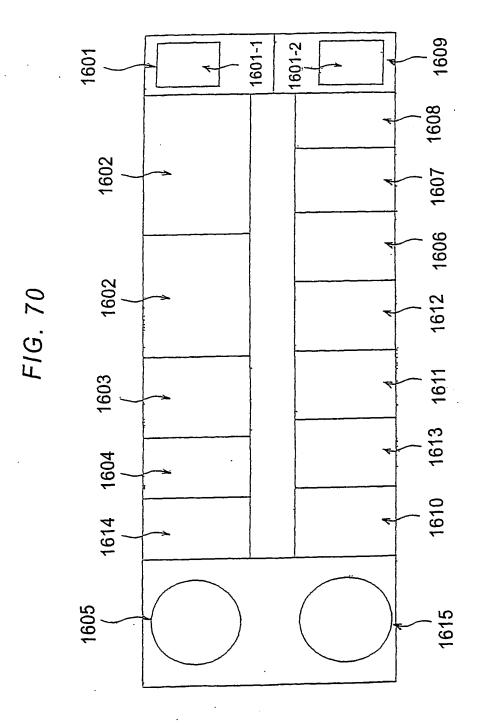


FIG. 71

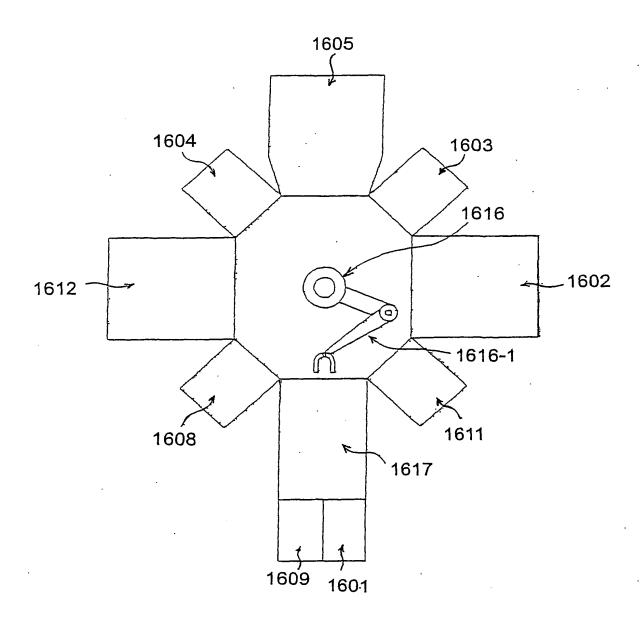


FIG. 72

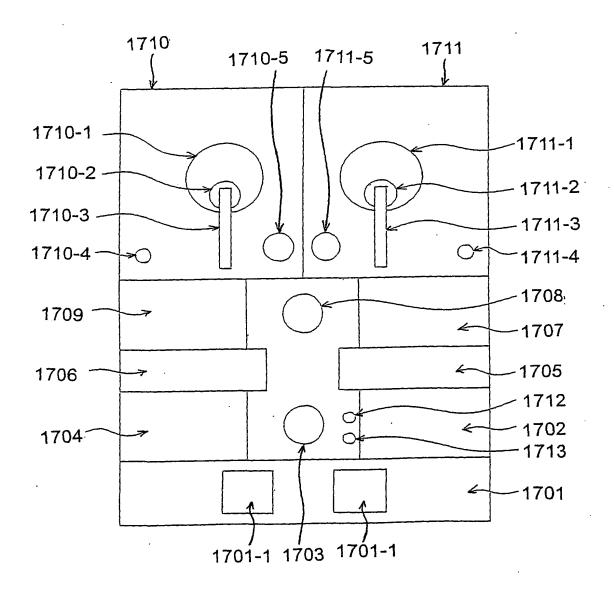
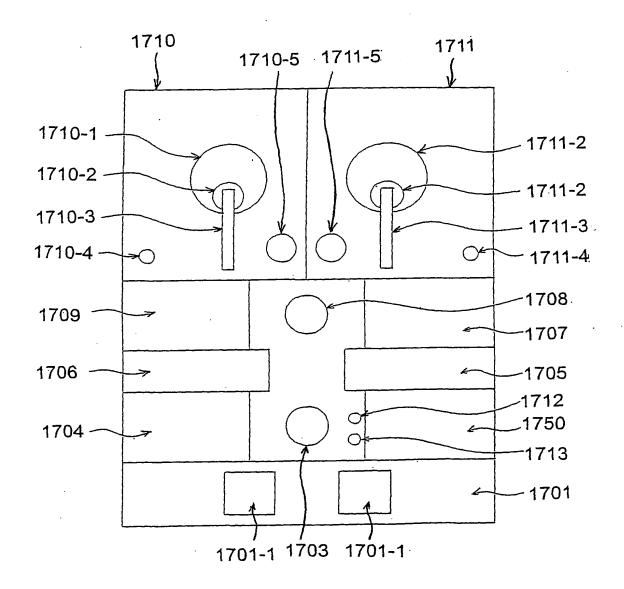


FIG. 73



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FIG. 74

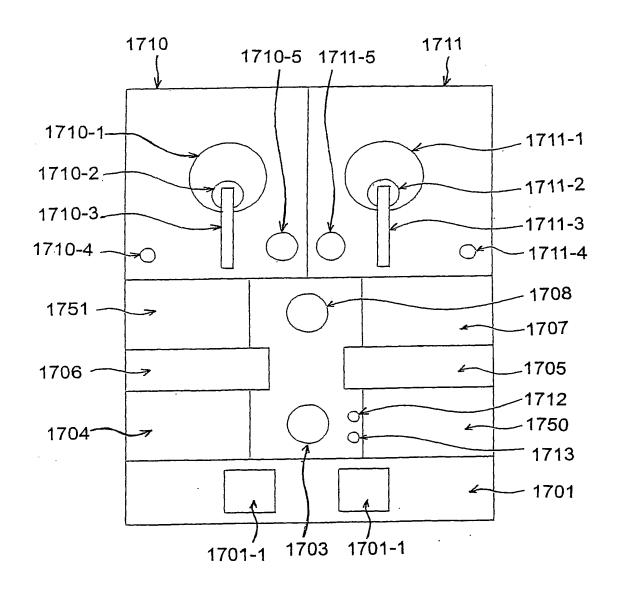


FIG. 75

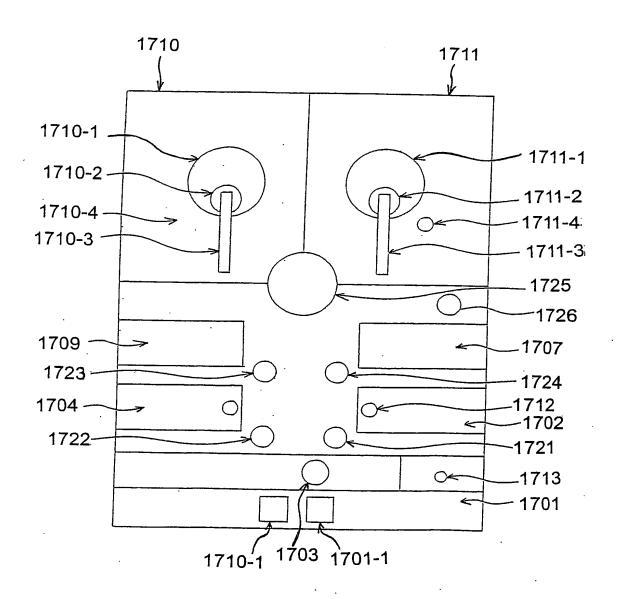
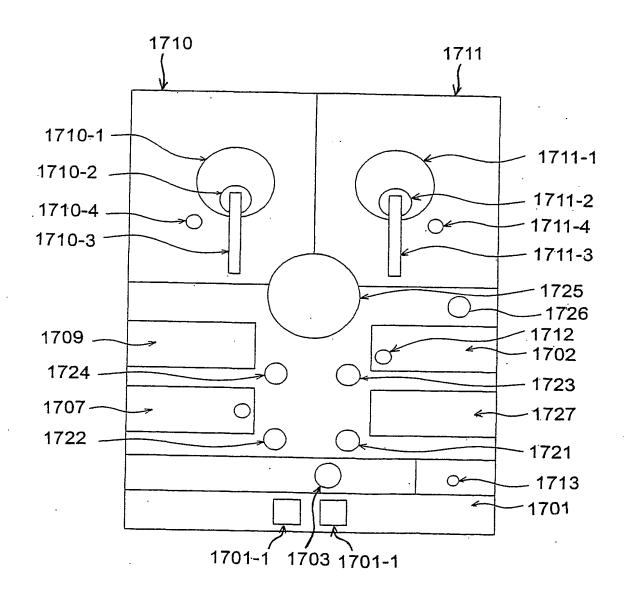
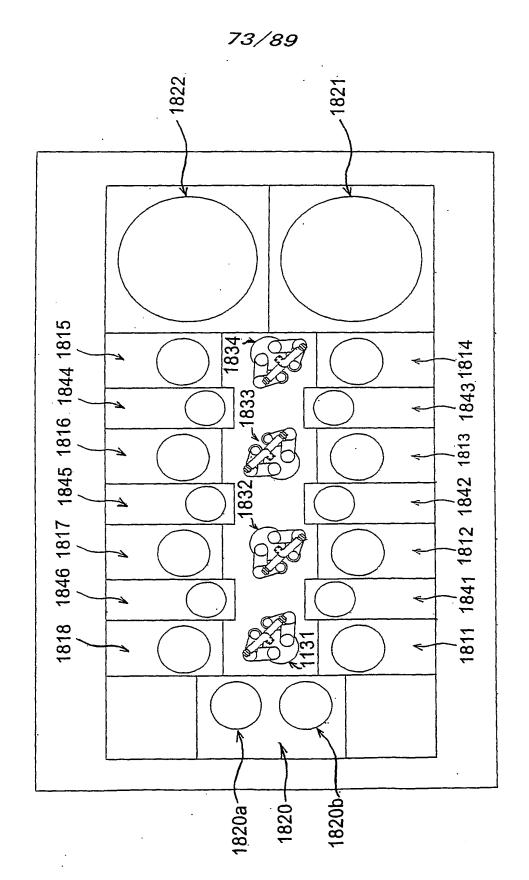


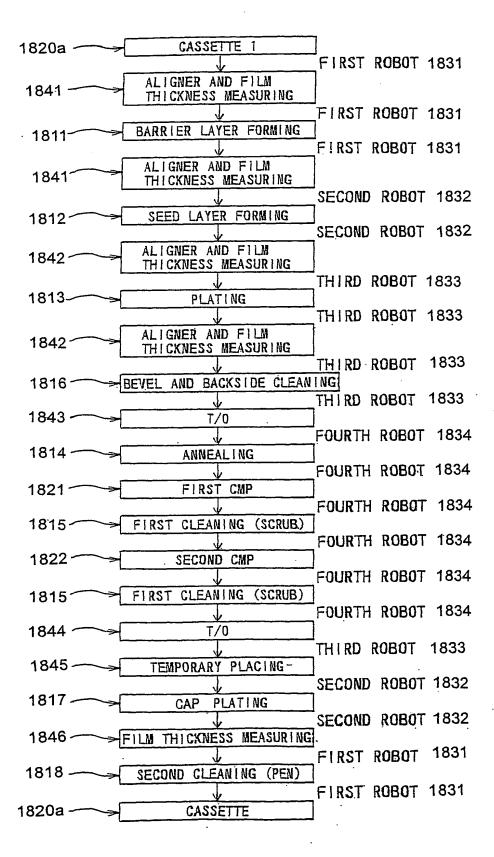
FIG. 76



F1G. 7



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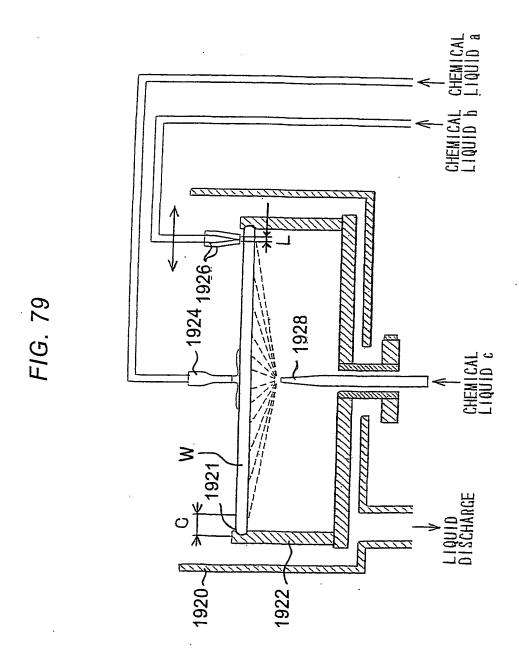


FIG. 80

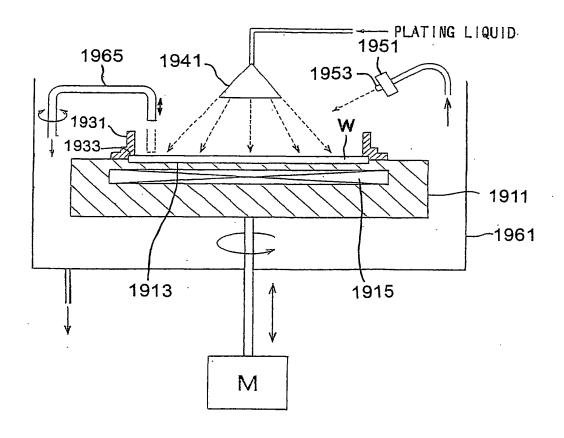
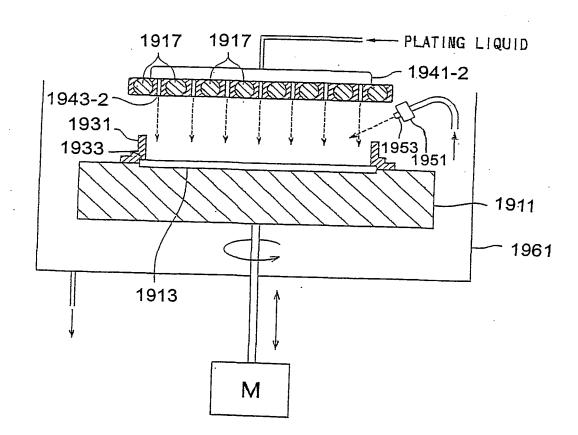


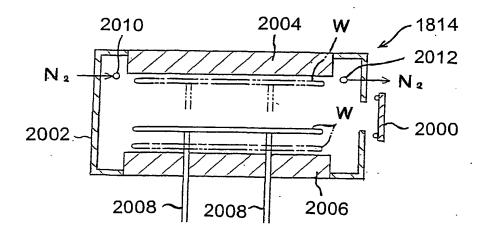
FIG. 81



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FIG. 82



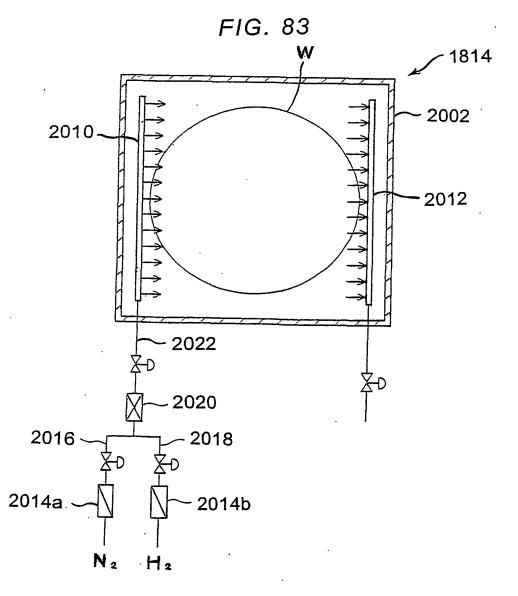


FIG. 84

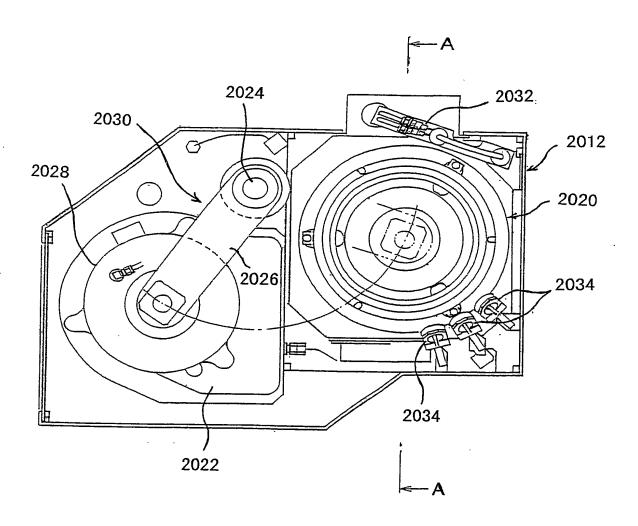


FIG. 85

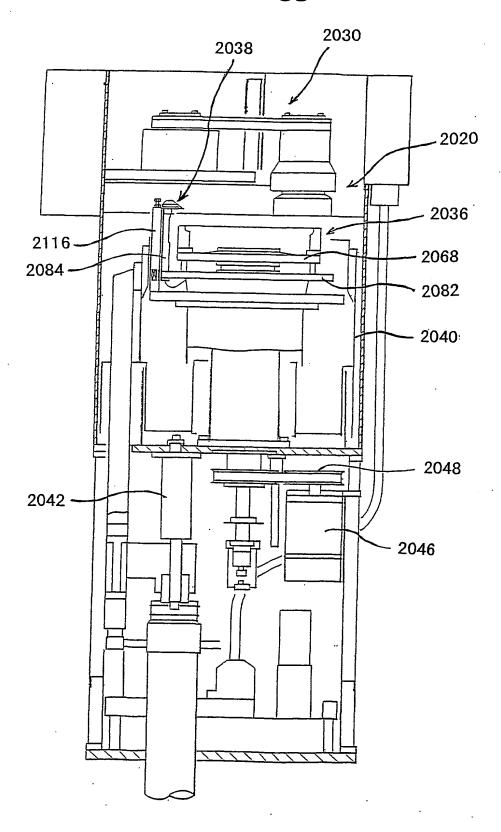
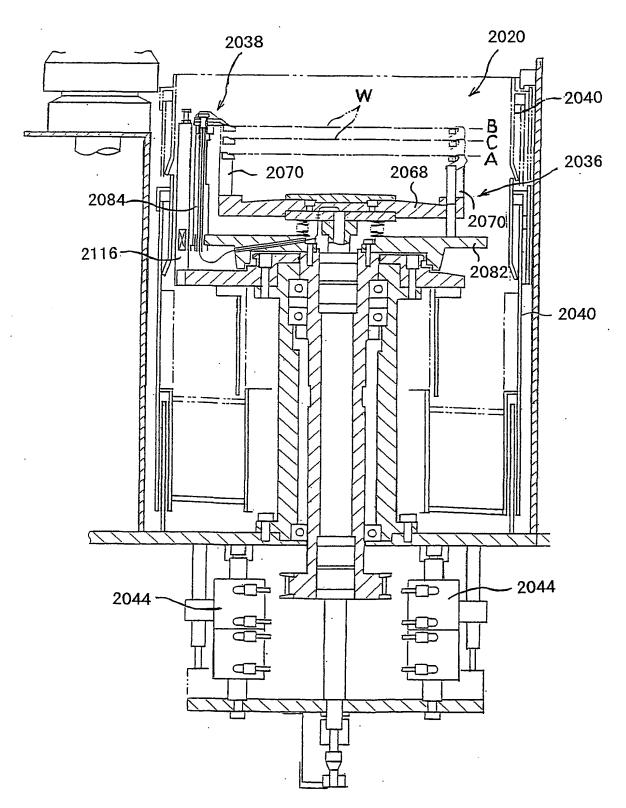


FIG. 86



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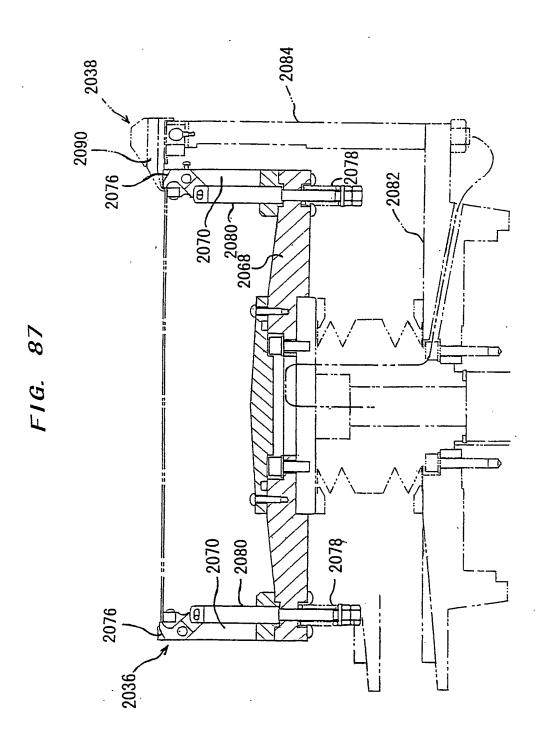
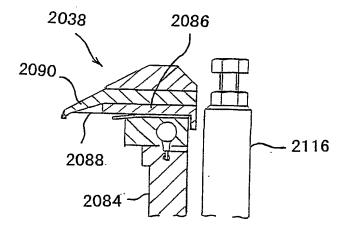
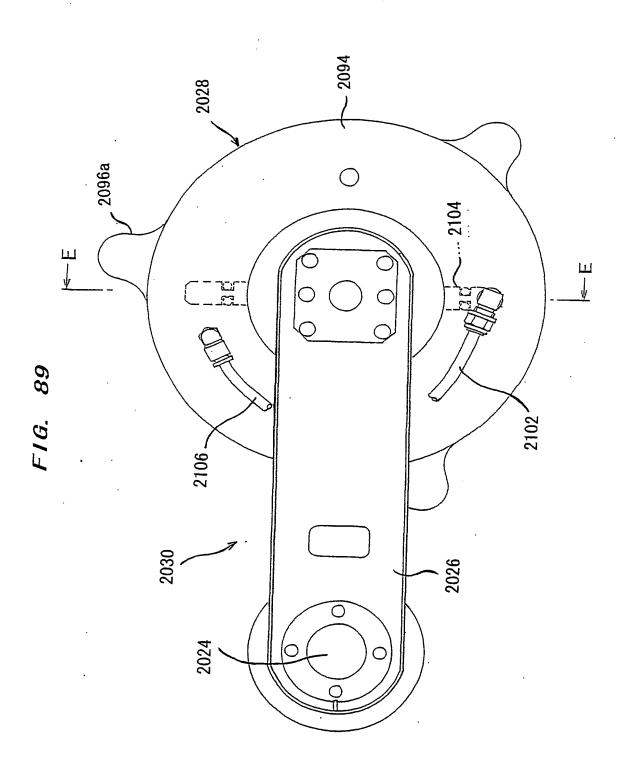
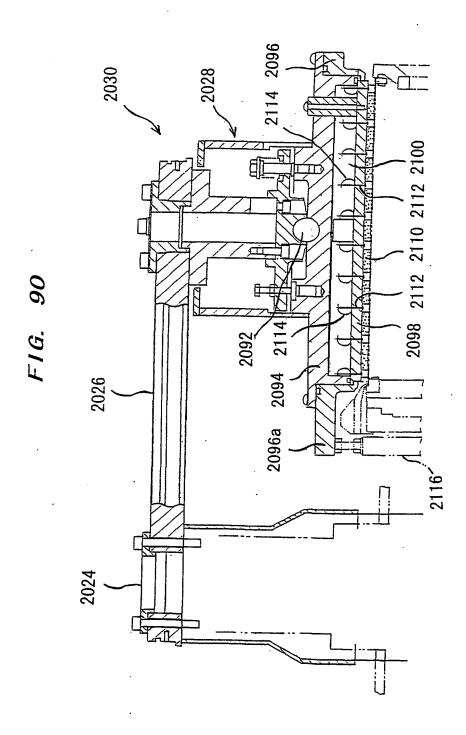


FIG. 88





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### FIG. 91

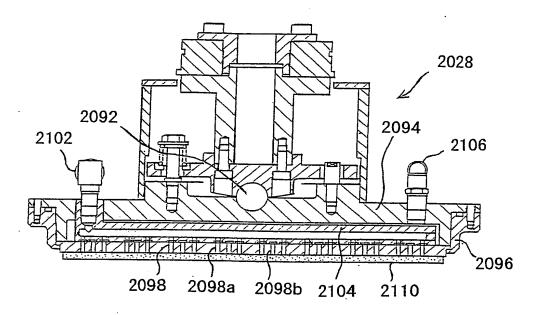


FIG. 92

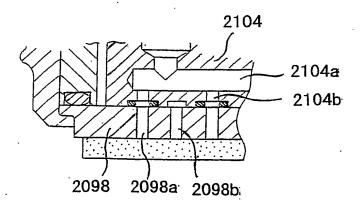


FIG. 93

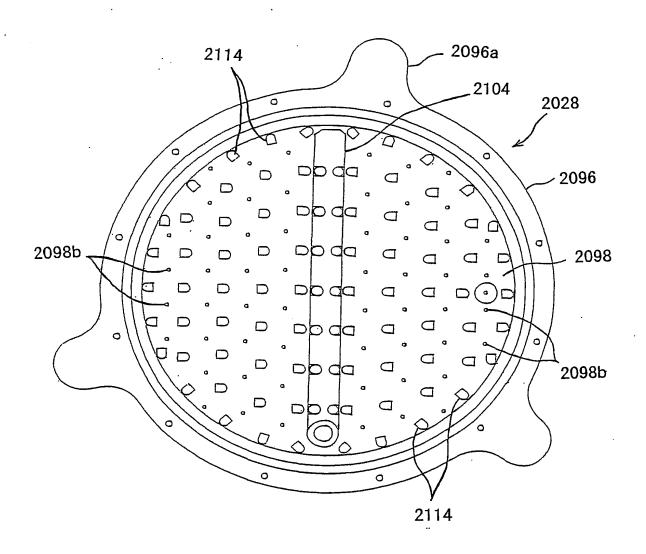


FIG. 94

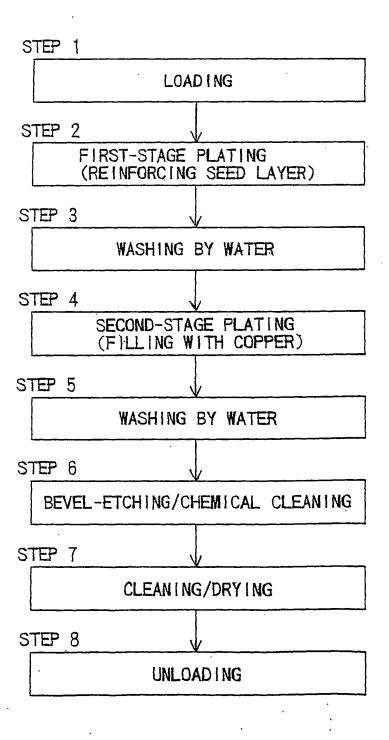


FIG. 95A

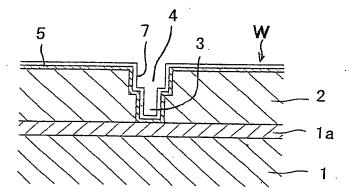


FIG. 95B

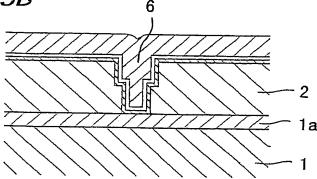


FIG. 95C

